

I.R.I.S.

INFRARED RELIABILITY INSPECTION SYSTEM

FINAL PRESENTATION

Group 3: Sean Willie, Andrew VanAuken, Jason Ha, Shea Meyer



MEET THE TEAM



Jason Ha

Photonic Science &
Engineering



Andrew VanAuken

Electrical
Engineering



Sean Willie

Electrical
Engineering



Shea Meyer

Computer
Engineering



PROBLEM & MOTIVATION

- Electrical equipment such as switchgear and transformers can develop overheating that may lead to equipment failure, downtime, and arc-flash hazards.
- Current thermal inspections are typically performed manually using handheld infrared cameras and only provide periodic snapshots of equipment.
- While infrared inspection windows improve safety, most monitoring solutions do not provide continuous temperature trending.
- The goal of IRIS is to develop a low-cost, thermal monitoring system that continuously detects hotspots and tracks temperature trends through existing IR windows.



Andrew VanAuken
EE



GOALS & OBJECTIVES

- **Continuous thermal monitoring of electrical equipment**
 - Monitor equipment through infrared inspection window.
- **Early hotspot detection**
 - Identify abnormal temperature rise.
- **Improve safety**
 - Reduce the need to open electrical enclosures.
- **Remote monitoring and alerts**
 - Provide temperature data and notifications through a web dashboard.



Andrew VanAuken
EE



ENGINEERING SPECIFICATIONS



Jason Ha
PSE

Parameter	Specification	Description
Imaging Temperature Range	40-120°C	Operating temperature range detectable by the system
Temperature Accuracy	±10°C	Maximum allowed measurement error
Field of View (FOV)	≥ 15° × 15°	Angular coverage of the monitored scene
Frame Rate	≥ 0.033 fps	Thermal image update frequency
Spatial Resolution	≤ 20 mm	Minimum feature size that can be resolved
Stimulus-to-Alert-Response Time	≤ 30 s	Time from anomaly detection to user alert
Hotspot Detection Accuracy	≥ 90%	Correct identification of thermal anomalies
False Alarm Rate	≤ 5%	Maximum allowable false hotspot detections
Data Update Rate	≥ 1 frame/min	Dashboard refresh frequency
Dashboard Latency	≤ 5 s	Delay between acquisition and display
Average Power Consumption	≤ 35 W	Average system power draw over one hour
Battery Life	≥ 4 hr	Continuous operating time on battery power
Signal-to-Noise Ratio (SNR)	≥ 10 dB	Minimum acceptable signal quality

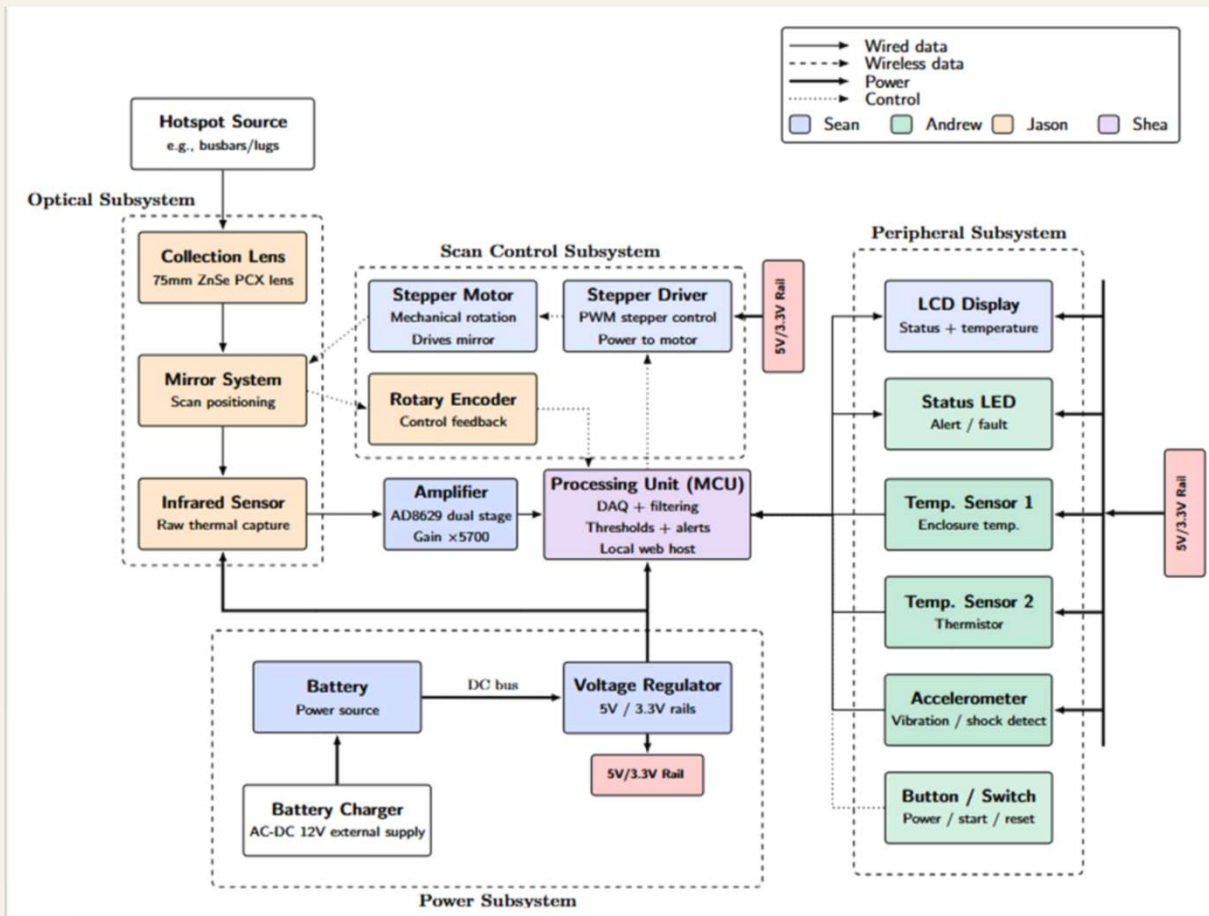
- Highlighted specifications are validated through testing
- Signal related specifications designed to account for small signal availability.



HARDWARE BLOCK DIAGRAM



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Key functions:

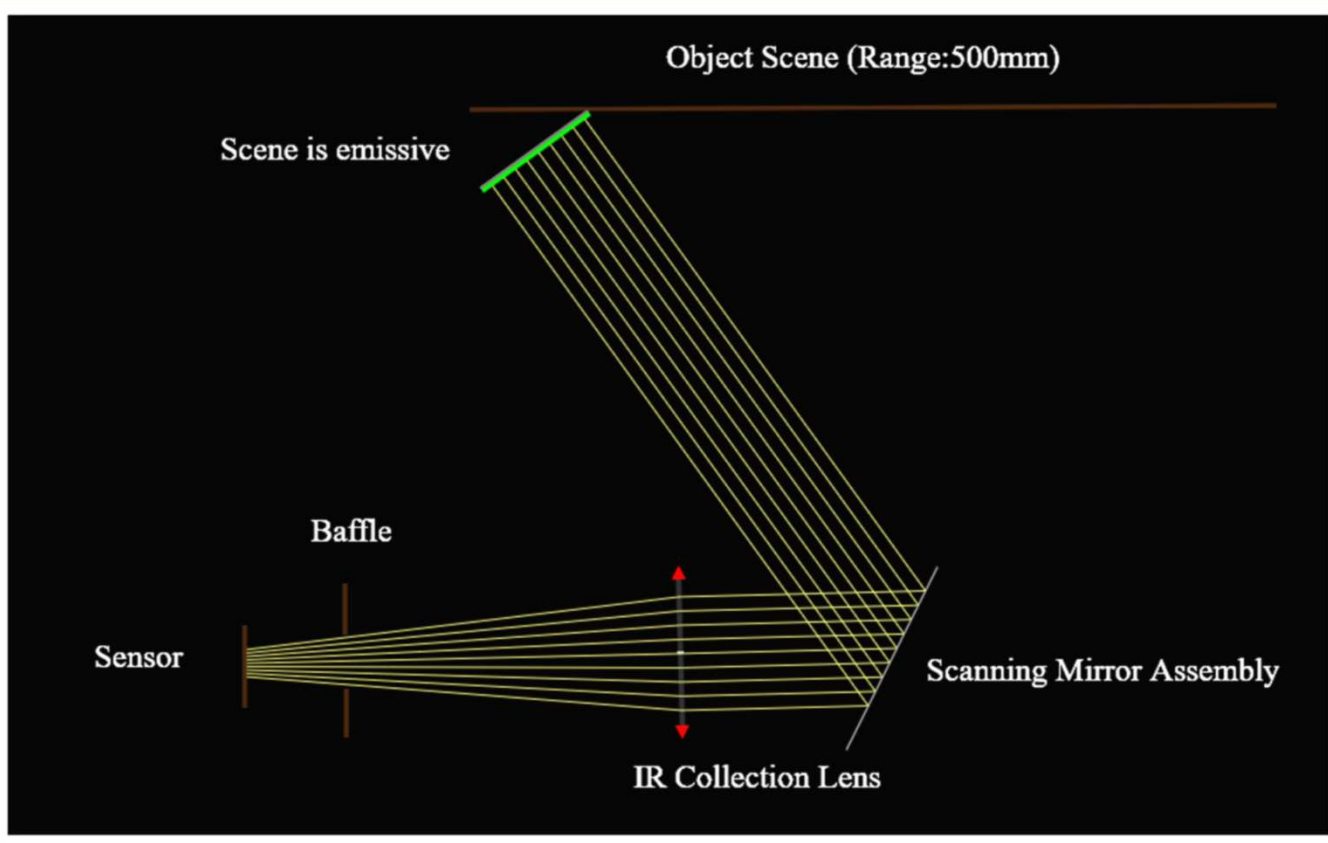
- Optics: Physical signal acquisition
- Amplification stage: Signal conditioning & processing
- Reliable mechanical scanning
- Supporting functions (power, displays, buttons)



OPTICS SCANNING SCHEMATIC



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- The mirror assembly sweeps the instantaneous view of the sensor across the target scene.
- Sensor and the location of the IFOV is described well by the law of reflection.
- Thermal measurements are collected point-by-point for image reconstruction.



IMAGING ARCHITECTURE SELECTION



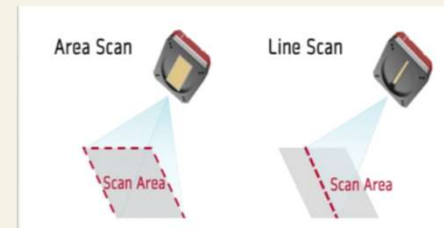
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Architecture	Advantages	Disadvantages
Line Scanning	Simplifies detector requirements	Requires controlled motion along two axes and larger mechanical assembly
Polygon Mirror Scanning	High-speed, precise scanning	IR-compatible components difficult to source and expensive
Raster Scanning	Cost-effective, highly controllable, compact design	Slower acquisition and sensitive to backlash

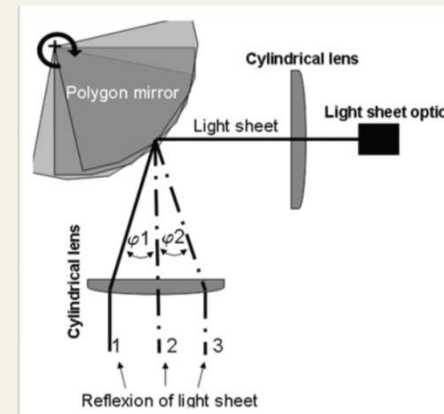
Reasons:

- Does not require motion of the target scene.
- Supports cost-efficient system implementation.
- Compact optical architecture.
- Compatible with the FOV requirements.

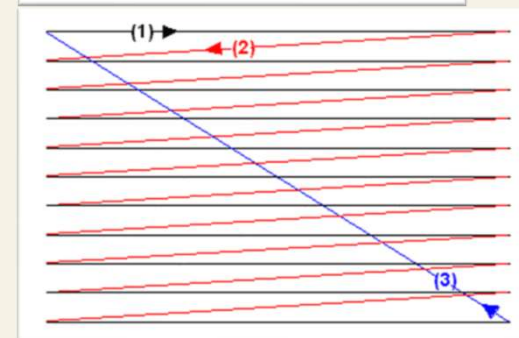
Raster scanning was chosen because it offers the best balance of cost, controllability, and implementation complexity while satisfying the project's imaging requirements.



Line Scanning



Polygon Mirror Scanning



Raster Scanning

INFRARED LENS/MIRROR SELECTION



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Parameter	Ge PCX 12.7 mm	Ge PCX 25 mm	ZnSe PCX
Material	Germanium	Germanium	Zinc Selenide
EFFL	50.8 mm	35 mm	75 mm
Spectral Range	2–14 μm	2–14 μm	0.6–18 μm
Approx. F/#	f/4	f/1.4	f/2
Price	\$270	\$655	\$312

Reasons:

- Both provide transmission in our target LWIR range.
- The selected lens sets our IFOV, and at 75mm creates a small IFOV for fully resolved imaging.
- Both are cost effective options in their performance class.

The ZnSe lens sacrifices some optical transmission, but is priced effectively, and readily available, unlike the similarly priced germanium lens.

Parameter	Thorlabs PF10-03-M02	Thorlabs PF10-03-M01	Thorlabs ME1-G01
Material	Mid-IR Enhanced Gold	Standard Protected Gold	Protected Aluminum
Diameter	25.4 mm (1 inch)	25.4 mm (1 inch)	25.4 mm (1 inch)
Spectral range	8–14 μm	0.8 – 20 μm	2 – 20 μm
Approx. reflectivity	~95% in LWIR	~96% in LWIR	~95% in LWIR
Price	\$76.01	\$70	\$36.67

THERMAL SENSOR SELECTION

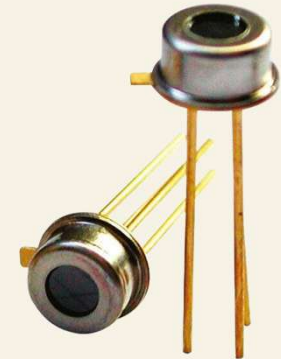


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Parameter	HMS J21 Thermopile with 8-14 um filter	Thorlabs TD2X Unmounted Thermal Power Detector	Amphenol Thermometrics ZTP- 135SR
Sensitivity	44 V/W	>0.1 V/W typ	62 V/W
Output referred noise	35 nV/ sqrt(hz)	35 nV/ sqrt(hz)	32 nV/ sqrt(hz)
Active area size	1.2 mm ²	4.0 mm ²	0.49 mm ²
Time constant	10 ms	~ 1.5 s (rise time)	25 ms
Field of view	120 degrees	120 degrees	85 degrees

Reasons:

- High sensitivity
- Does not include internal optics, it's effective field of view will be determined by our implementation
- Low Output Referred Noise density
- Fast time constant
- Important: Filter has some absorbance, and re-emittance will happen.



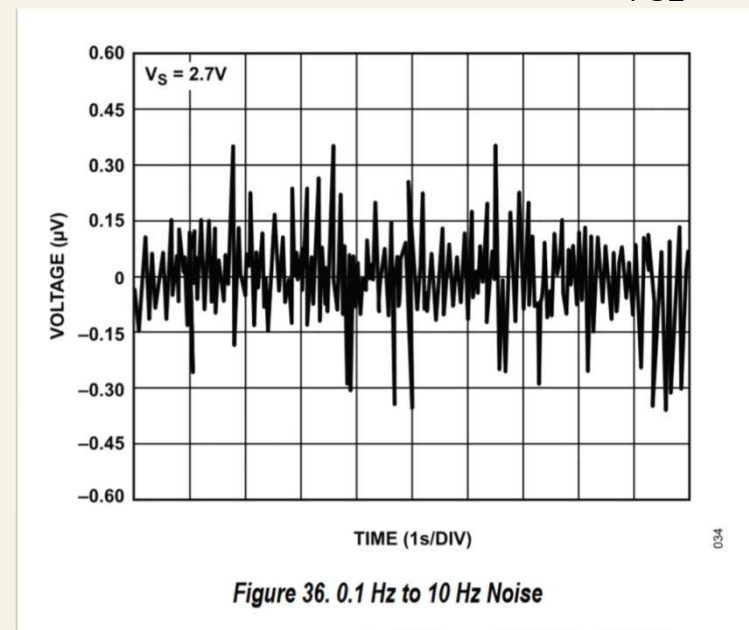
SIGNAL AMPLIFIER SELECTION

Parameter	AD8629	INA333	AD8421
Amplifier technology	Zero-drift chopper	Instrumentation amp	Three op-amp instrumentation amp
0.1-10 Hz Noise	0.5 μV p-p typ	1 μV p-p typ	1.5 μV p-p typ
Voltage drift	0.002 $\mu\text{V}/^{\circ}\text{C}$ typ	0.1 $\mu\text{V}/^{\circ}\text{C}$ typ	0.2 $\mu\text{V}/^{\circ}\text{C}$ max
Voltage offset	1 μV typ	25 μV typ	25 μV typ
Input bias current	100 pA max	200 pA typ	500 pA max

- Temperature drift was a large concern; AD8629 had performance orders of magnitude better.
- High performance in low-frequency noise
- Highly relevant reference circuits available- assists with analog design



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AD8629 Input Referred Noise

PROCESSING UNIT SELECTION

Parameter	MSP430	Raspberry Pi	ESP32-S3-WROOM-1
Clock Speed	~16-25 MHz	~1.5 GHz	240 MHz
Flash Memory	KB range	MicroSD storage	4 MB
SRAM / RAM	KB range	1-8 GB	512 KB
Wi-Fi	No	Yes	Yes
Power Consumption	Very Low	High	Low-moderate

Reasons:

- Integrated Wi-Fi connectivity.
- Supports required peripherals and interfaces.
- Sufficient processing capability.
- Low cost and power consumption.

The ESP32-S3 provides significantly greater connectivity and processing capability than traditional microcontrollers while maintaining lower power consumption and cost.



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MOTION CONTROL SELECTION

Parameter	28BYJ-48	17HE08-1004S	SF2421-10B11
Operating Voltage	5 V	8–35 V	24 V
Step Angle	5.625°/64 (0.088° effective)	1.8°	1.8°
Steps/Rev	2048	200	200
Holding Torque	34.3 mN·m	170 mN·m	290 mN·m
Rated Current	~160 mA	1 A/phase	1 A/phase

Reasons:

- Compatible with the 5 V power rail.
- High positional resolution for raster scanning.
- Sufficient torque for mirror actuation.

While larger bipolar steppers provide higher torque, the 28BYJ-48 offers the best balance of resolution, power compatibility, simplicity, and cost for the IRIS raster scanning system.



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TEMPERATURE SENSOR SELECTION



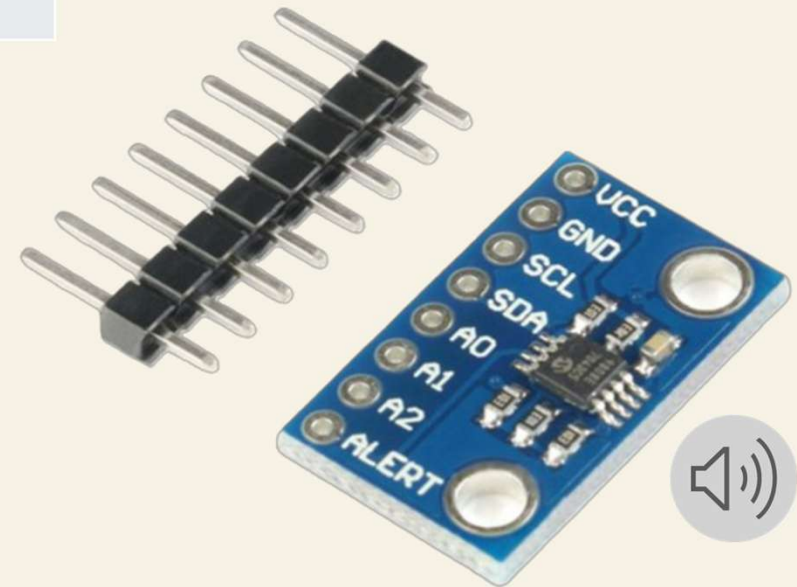
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Parameter	DS18B20	MCP9808	TMP102
Interface	1-Wire	I ² C	I ² C
Accuracy	±0.5°C	±0.25°C	±0.5°C
Operating Voltage	3.0–5.5 V	2.7–5.5 V	1.4–3.5 V
Cost	\$3–6	\$4–6	\$8–12

Reasons:

- Highest measurement accuracy.
- I²C communication.
- Compatible with ESP32 platform.
- Low power consumption.

The MCP9808 provides improved accuracy and simple integration at a slightly higher cost than basic temperature sensing solutions.



POWER SYSTEM SELECTION



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Parameter	Ni-Cd	Ni-MH	Li-Ion
Nominal Cell Voltage	1.25 V	1.25 V	3.6 V
Gravimetric Energy Density	~50 Wh/kg	~90 Wh/kg	~210 Wh/kg
Self-Discharge / Month	15–20%	20–30%	5–10%
Cycle Life	>1,000	~500	~500–1,000

Component	Selected	Reason
Battery Pack	Talentcell PB006B3	12.6–9.0 V DC output, DC5521 connector, included charger
5 V Regulator	LM2596 Buck	3 A output rating; supports motor/display rail
3.3 V Regulator	AMS1117-3.3	Low-noise rail for ESP32 and sensors

Reasons:

- High energy density minimizes battery size and weight.
- Low self-discharge supports intermittent deployment.
- Supports the 4-hour runtime requirement.

Li-Ion provides the best balance of runtime, size, and weight while requiring battery protection and charging circuitry.



COMMUNICATION TECHNOLOGY SELECTION



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CpE

Feature	Wi-Fi	Bluetooth LE	Zigbee	LoRa
Typical Data Rate	54+ Mbps	Up to 2 Mbps	Up to 250 kbps	0.3–50 kbps
Operating Range	~45 m indoors	~10–100 m	~10–100 m	Up to 15 km
Power Consumption	High	Very Low	Low	Very Low
Native IP Support	Yes	No	No	No
ESP32-S3 Native Support	Yes	Yes	No	No

Reasons:

- Direct IP support for web dashboard communication.
- Built into the ESP32-S3, so no external module is required.
- Better fit for local monitoring than long-range, low-data-rate options.

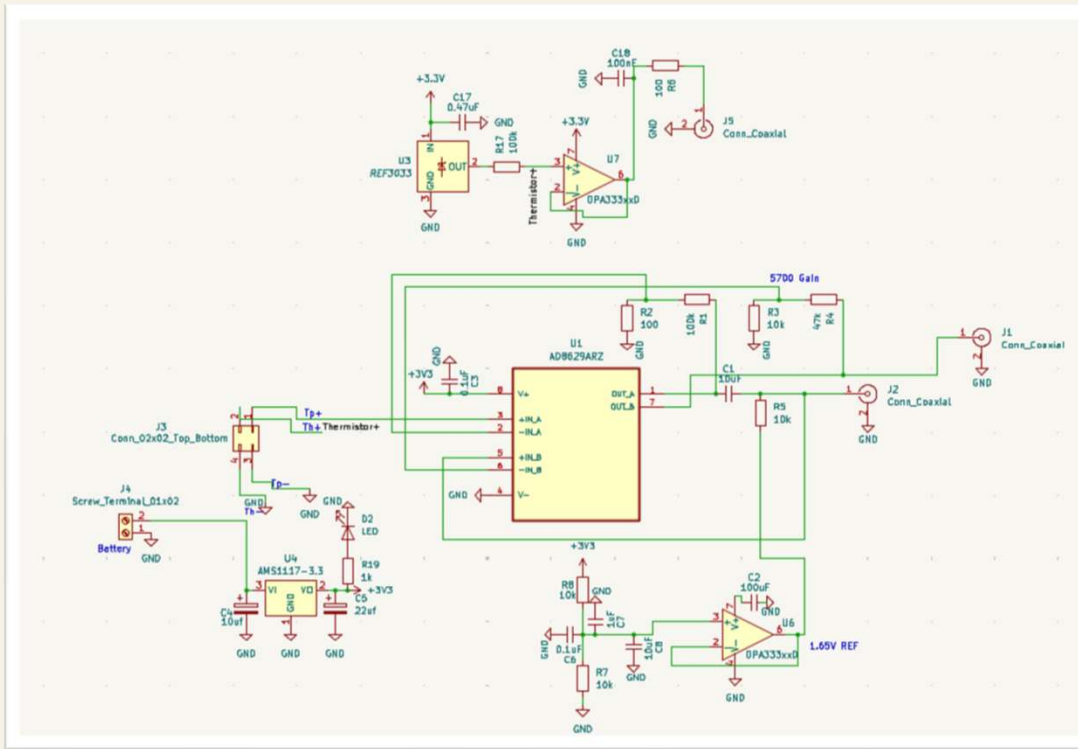
Wi-Fi consumes more power, but it provides the direct web connectivity needed for IRIS.



THERMOPILE PREAMPLIFIER SCHEMATIC



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EE



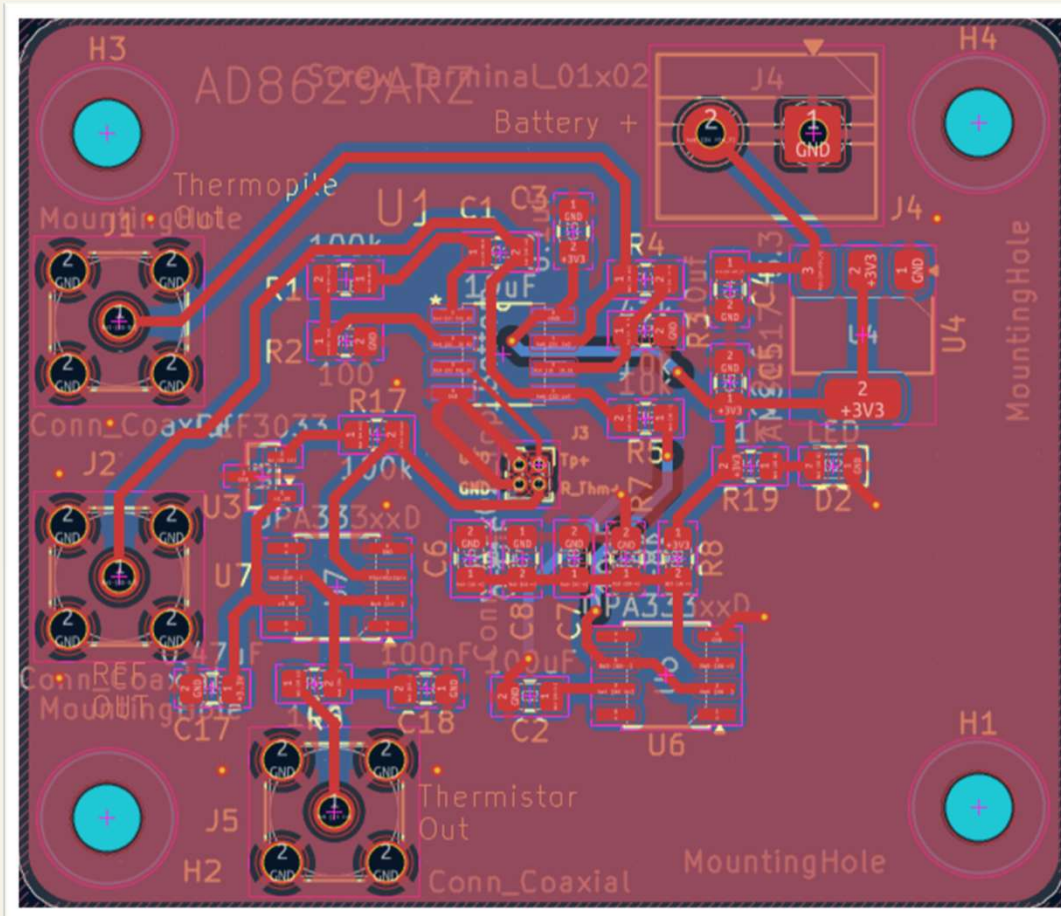
- Our dedicated preamplifier board has separate power delivery (AMS1117) to reduce noise from the switching 5V regulator.
- AD8629 is used for the thermopile, while OPA333 is used for separate thermistor input amplification
- The gain (50000) brings us to a high enough level (0.5V–2.5V) for the ADC to read the thermopile
- The output is sent through coaxial cables to reduce interference from outside devices.



THERMOPILE PREAMPLIFIER PCB DESIGN



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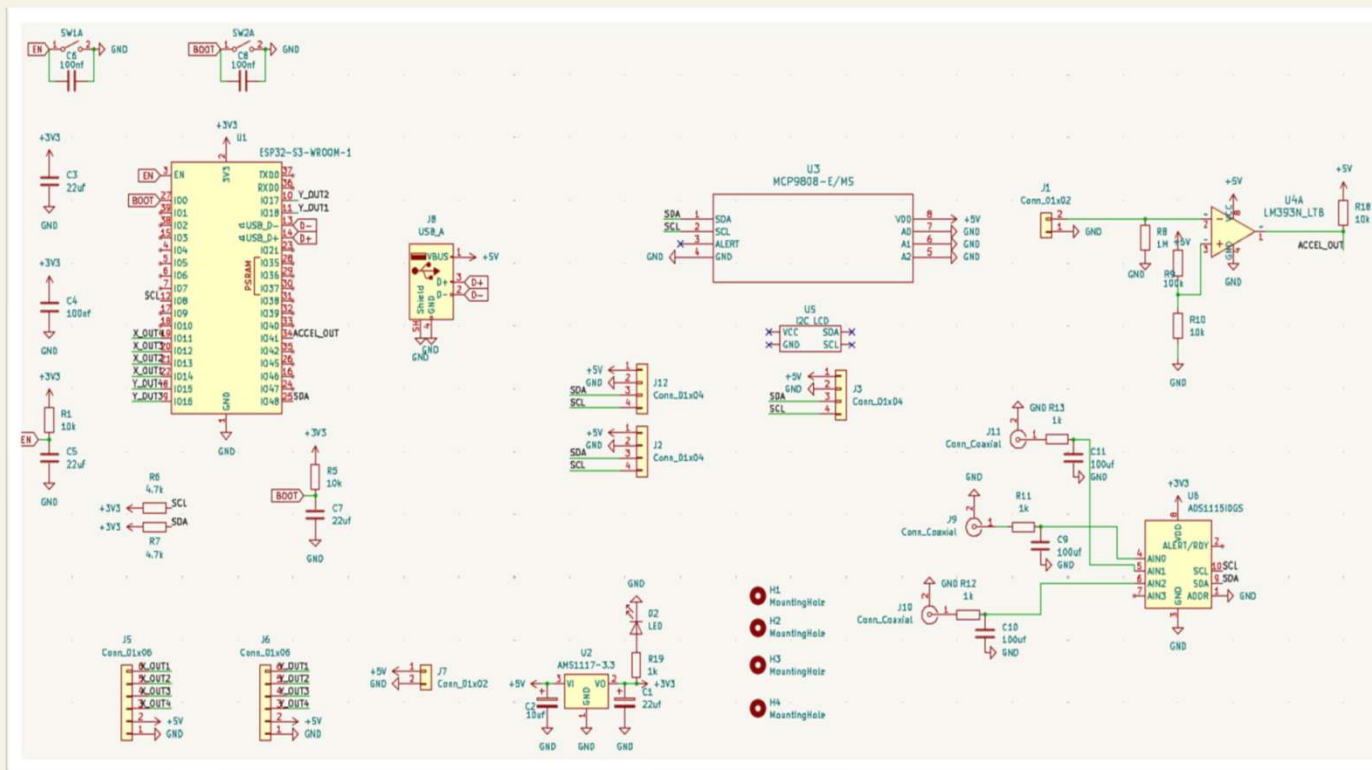
- The PCB design for the preamplifier meets the constraints of size and profile, fitting inside the lens tube.
- Input signal traces from the thermopile were kept as short as possible, to reduce electromagnetic interference.
- Thermopile input is put in the center, to mount the sensor center for the lens.



MCU & PERIPHERAL SCHEMATIC



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EE



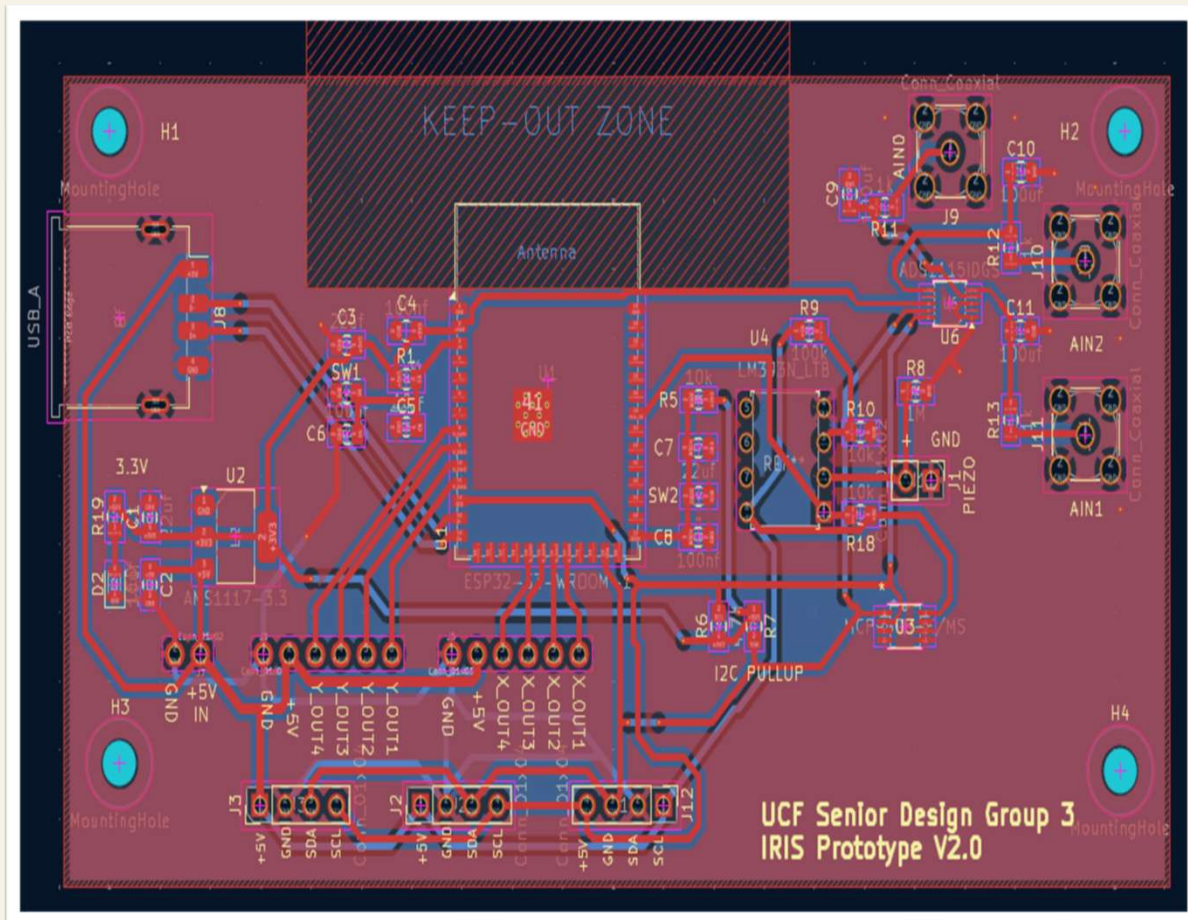
- The main MCU board contains the ESP32, MCP9808 temperature sensor, ADS1115 ADC, LM393 comparator, AMS1117 regulator, as well as connections for the drivers and external display.
- The MCU processes the infrared image and controls the scanning system.



MCU & PERIPHERAL PCB DESIGN



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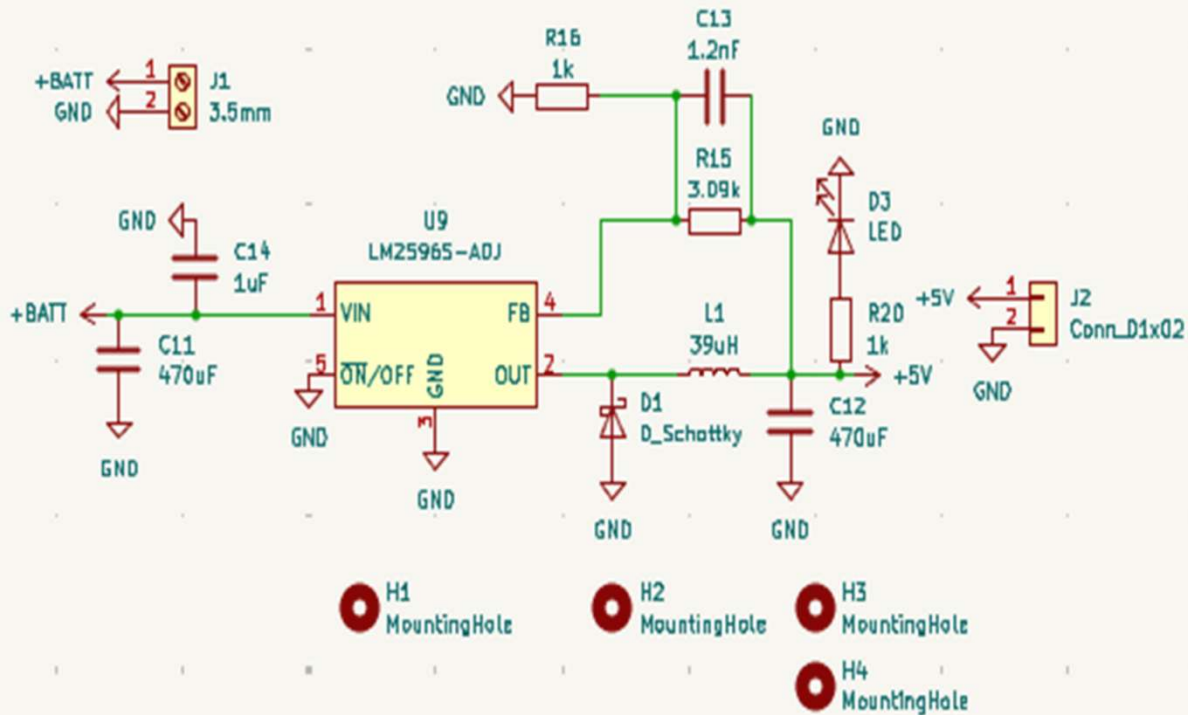


- The MCU PCB is designed to reduce the noise transfer to the analog inputs.
- Digital connections are kept on the left and bottom side, while analog connections are on the top right corner.
- Analog connections are as close to the ADC as possible to avoid interference from I2C lines.
- Stepper drivers are given larger traces to power the motors.

5V REGULATOR SCHEMATIC



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EE



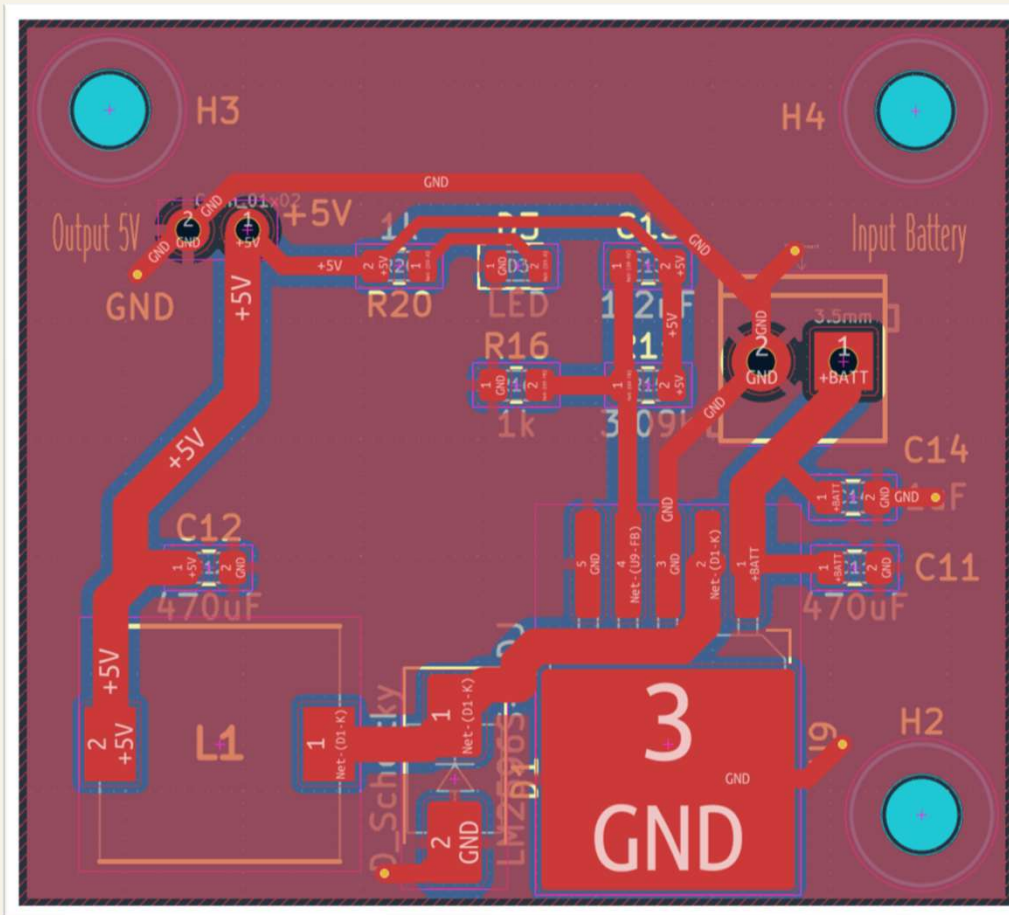
- The 5V regulator takes the battery input and ensures it is kept in a safe range for the MCU and components.
- Design choices were made based on the datasheet from TI and outside references.
- The regulator is kept on a separate board to give modularity in case of failure.



5V REGULATOR PCB DESIGN



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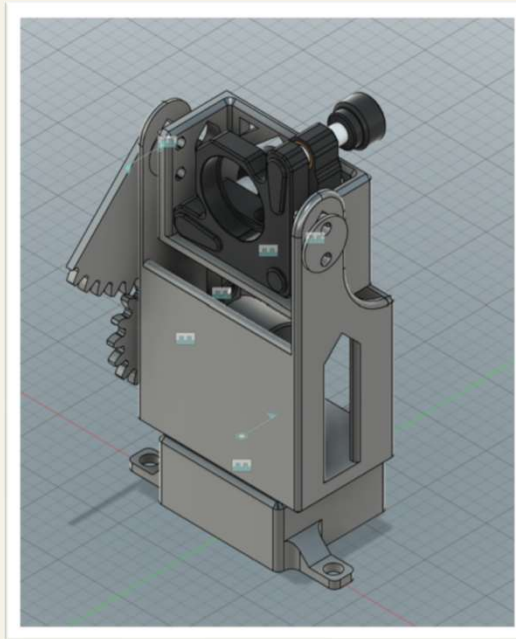
- The 5V regulator PCB is designed to ensure stable power delivery for the entire system.
- Power traces were made thick to avoid overheating.
- An output LED was added for troubleshooting and ensuring output.



OPTO-MECH DESIGN: MIRROR SCANNER

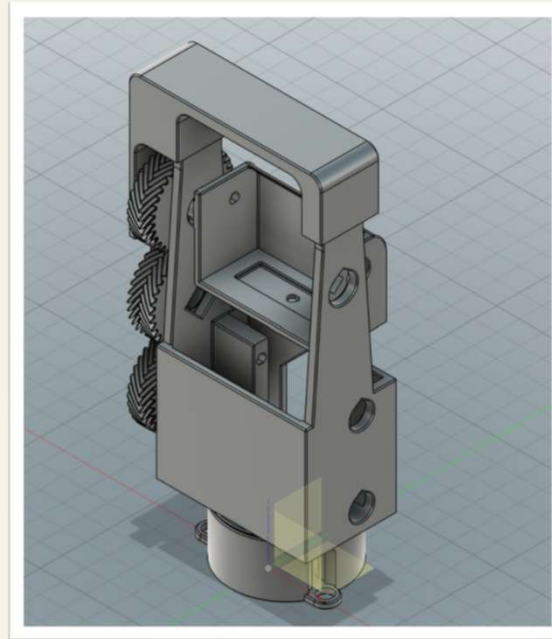
Key Functions:

- Reliability scanning
- Appropriate accuracy
- Compatible with external hardware (such as encoders, motors, optics mounts)



Gimbal v1.2

- Established basic functions
- Characterization revealed flaws in design/implementation
- Confirmed engineering assumptions



Gimbal v2.2

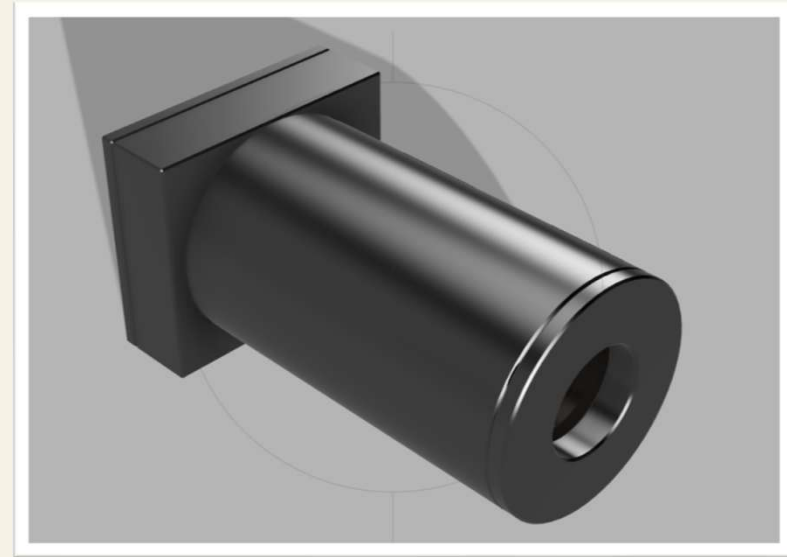
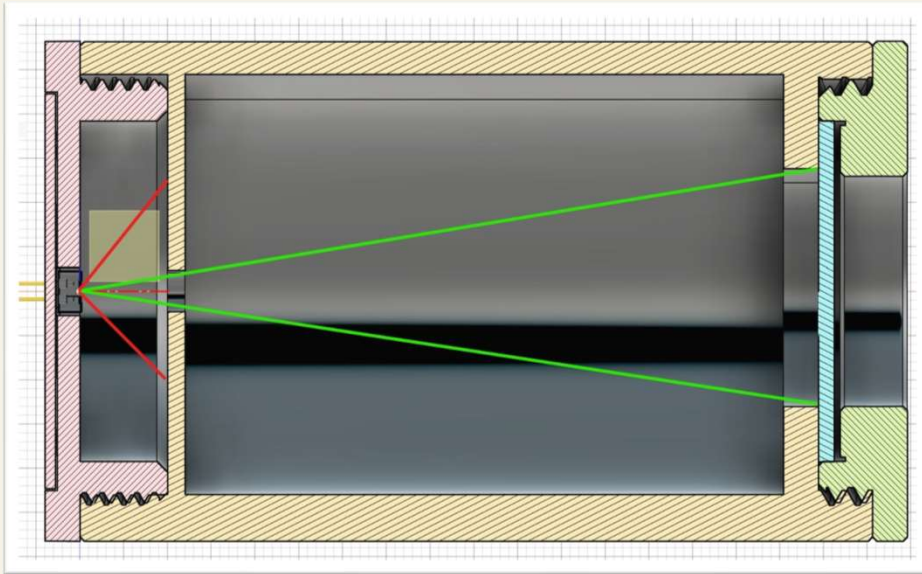
- Herringbone Gears decrease effective backlash/torque transmission loss
- Metal bearings decrease resistance and improve reliability
- Geometry results in more rigidly defined structure



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OPTO-MECHANIC DESIGN: LENS TUBE + BAFFLE



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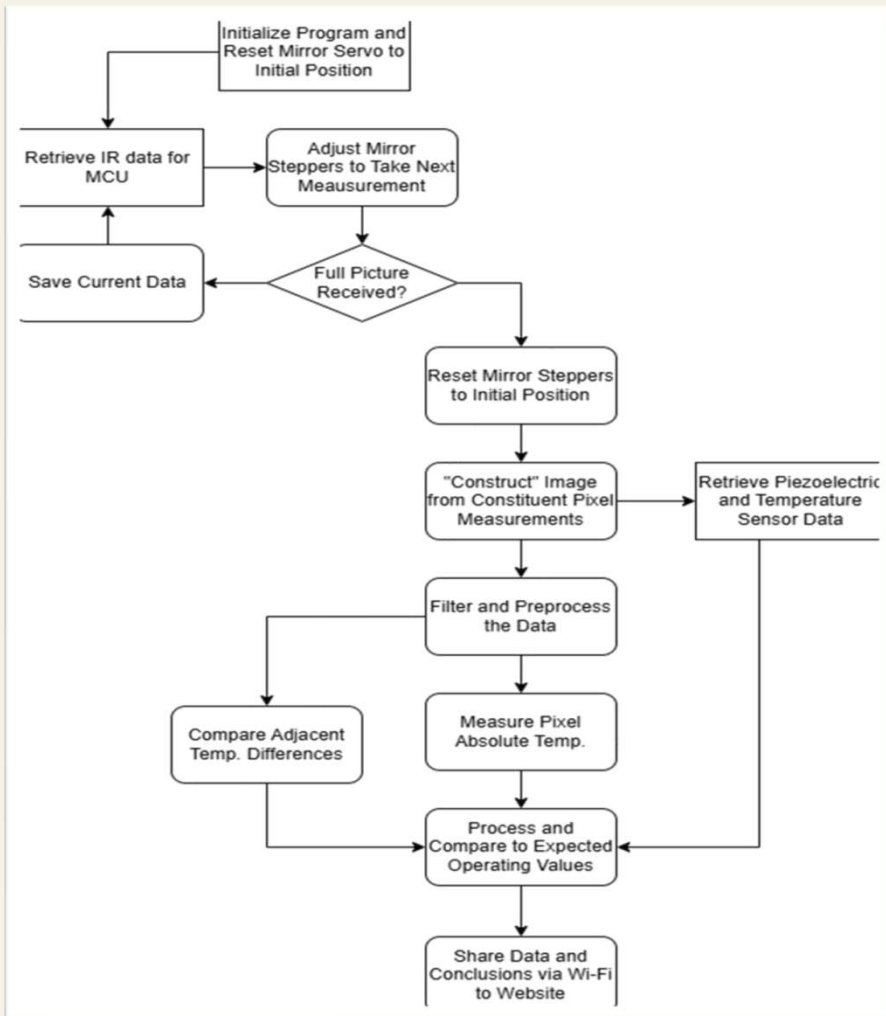
- Threaded insert design allows for fine adjustment to place sensor at position of best signal.
- The high friction of the plastic threads removes concern for misalignment.
- The integrated optical baffle reduces background and stray radiation while also lowering re-emittance.



ESP32 SOFTWARE ARCHITECTURE



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CpE



- Coordinates sensing, raster scanning, and peripheral control.
- Organizes firmware using concurrent FreeRTOS tasks.
- Process thermal measurements and hotspot detection.



LANGUAGE SELECTION



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Reasons:

- Familiar and reliable.
- Low overhead.
- Strong ESP32 support.
- Works well with FreeRTOS.

Feature	C	C++	MicroPython
Library Availability	High	Highest	Moderate
Familiarity	High	Low	Moderate
Ease of Use	Moderate	Low	High
Suitability	High	Moderate	Moderate



FRAMEWORK SELECTION

Feature	Arduino	ESP-IDF
Ease of Use	High	Moderate
ESP32 Support	Good	Excellent
RT Support	Limited	Strong
Low-Level Control	Limited	High
Familiarity	Moderate	High

Reasons:

- Official ESP32 framework.
- Better real-time support.
- Greater hardware control.



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REAL TIME TASK OVERVIEW

Tasks	Purpose
stepper_task	Manage raster scanning
encoder_task	Measures from rotary encoder
POST_task	Receive all data and post to backend server
temperature_task	Sending ambient temperature data
vibration_task	Sending piezoelectric data

Features:

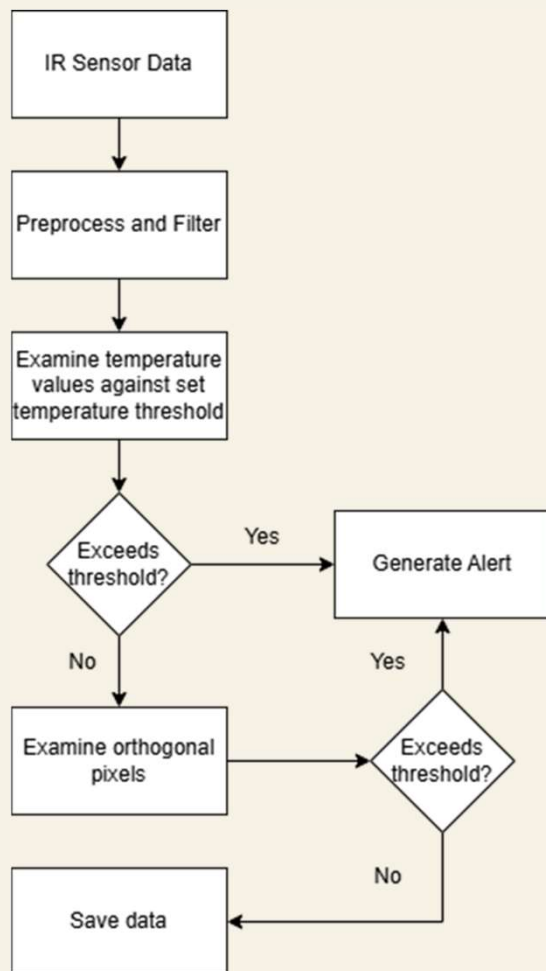
- Execution of sensing, motion, and communication tasks.
- Modular task separation simplifies development and debugging.
- Continuous system operation during raster scanning.



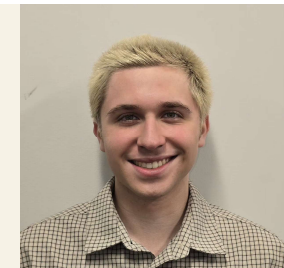
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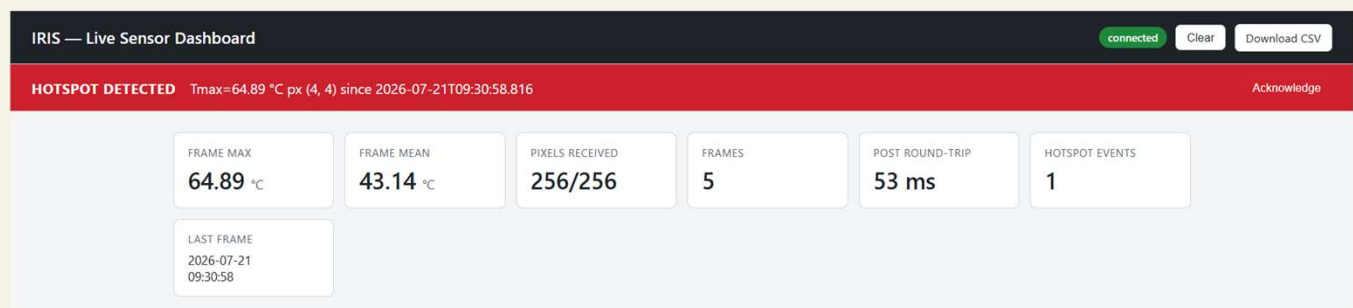
HOTSPOT DETECTION ALGORITHM



- Filters and evaluates thermal measurements.
- Applies threshold-based hotspot detection.
- Generates alerts for abnormal conditions.



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WEB BACKEND SELECTION



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Feature	Python	Go	Node.js
Performance	Moderate	High	High
Real-Time Support	Moderate	High	High
Familiarity	High	Low	Low
Full-Stack Capability	No	No	Yes

Reasons:

- Real-time data streaming.
- Unified frontend/backend language.
- Easy integration.

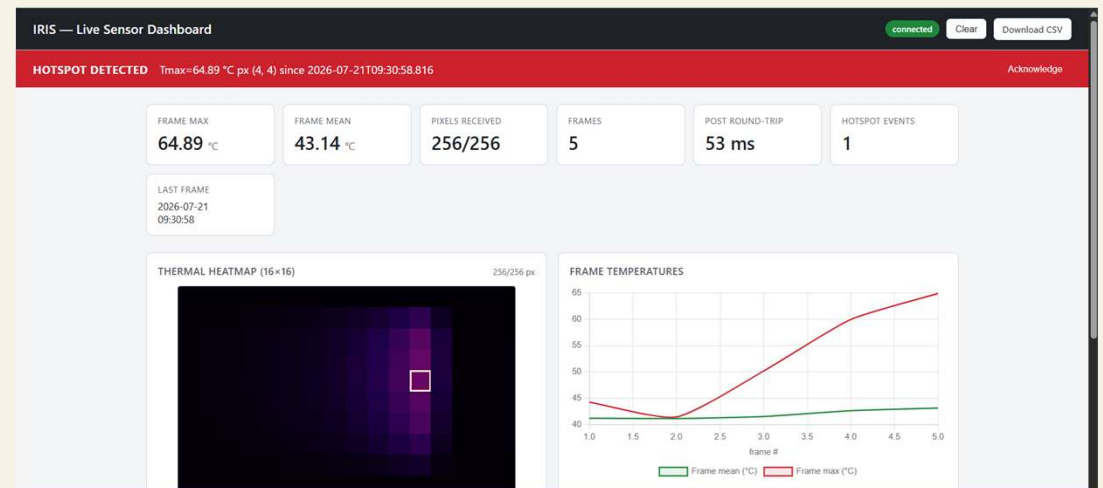


WEB DASHBOARD SELECTION



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Feature	HTML/JS	React	Vue
Learning Curve	Low	High	Moderate
Component Reuse	Low	High	High
Real-Time Updates	Manual	Built-In	Built-In
Visualization Libraries	Limited	Extensive	Moderate



Reasons:

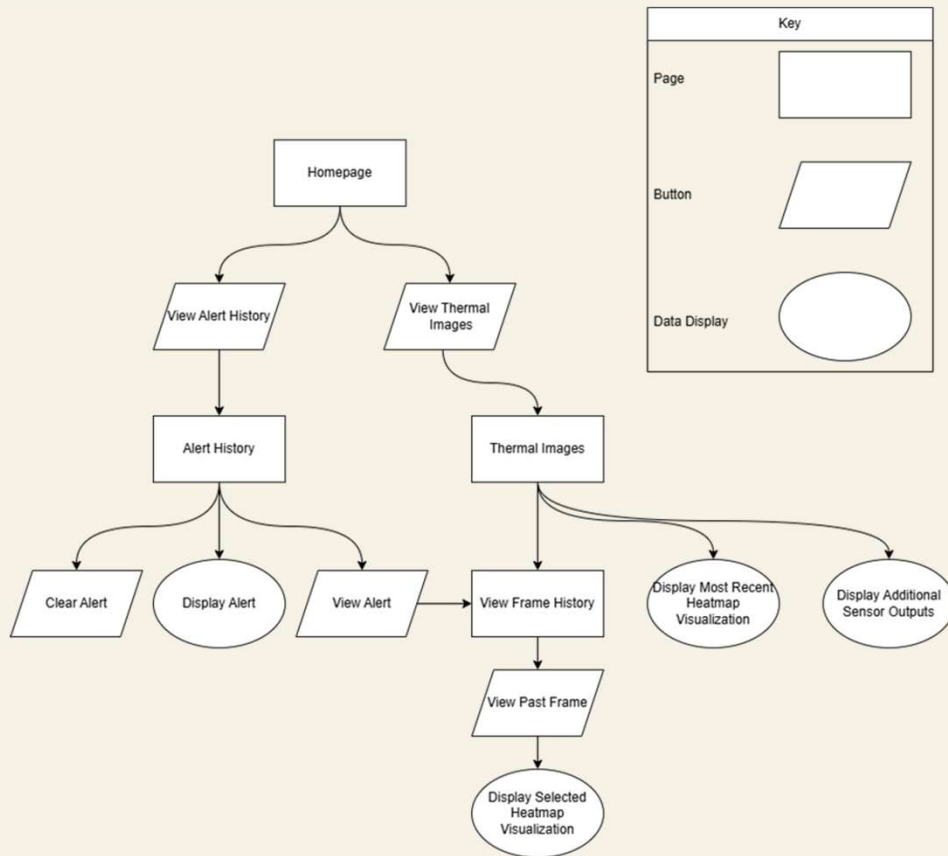
- Component-based architecture.
- Strong visualization support.
- Ideal for thermal heatmaps.



WEB UI FLOW



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- View live thermal images and sensor data.
- Review alert history and hotspot events.
- Access scan data history and previous heatmaps.



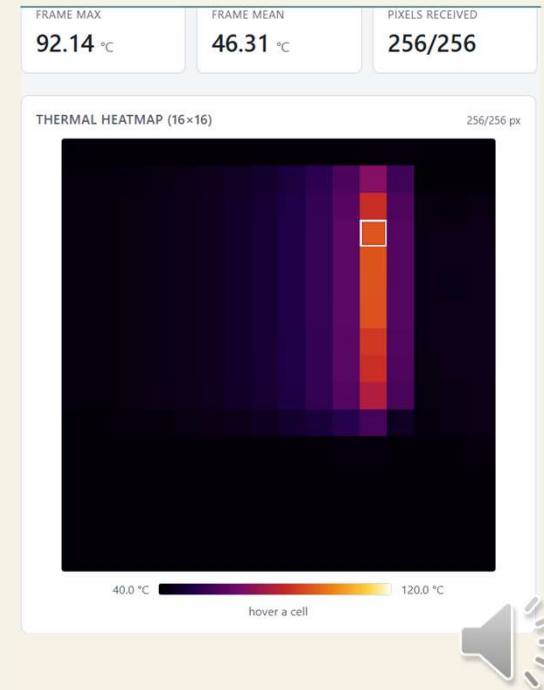
WEB HOSTING AND COMMUNICATION



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Layer	Selected Technology	Role
Backend Runtime	Node.js	HTTP server, real-time event handling
Backend Framework	Express	Routing, middleware, API endpoints
Real-Time Communication	Socket.IO	Streaming thermal grids and alerts to browser
Visualization	React + Canvas/SVG Library	Thermal heatmap rendering
Data Storage	SQLite	Scan history and alert persistence
ESP32 Backend Protocol	HTTP POST (JSON) over Wi-Fi	Periodic scan upload from ESP32

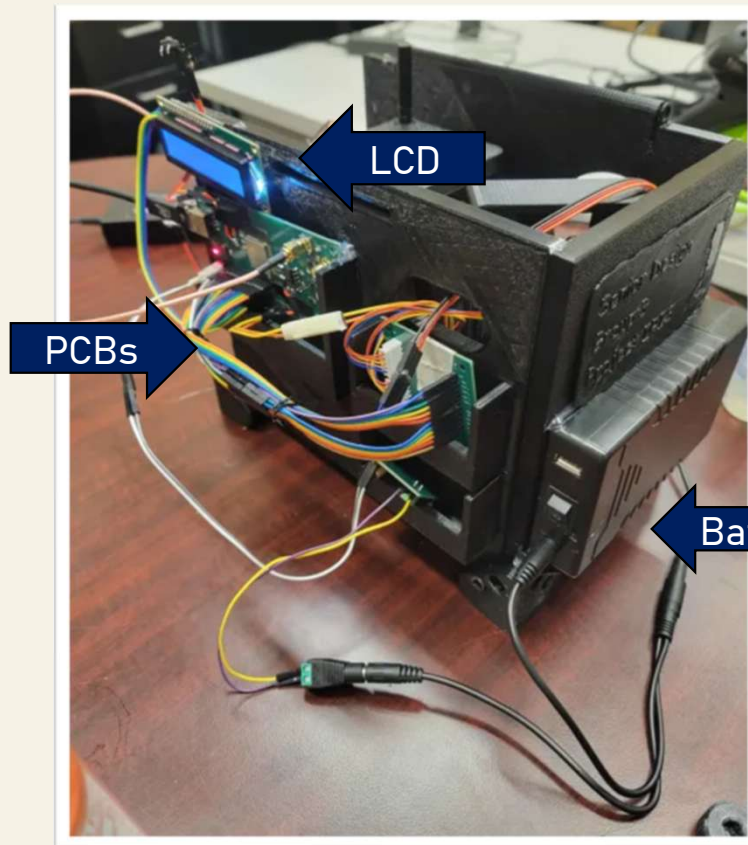
- Displays live thermal images and system status.
- Provides hotspot alerts and event history.
- Supports review of previous thermal scans and sensor data.
- Locally hosted on ESP32 for browser-based access.



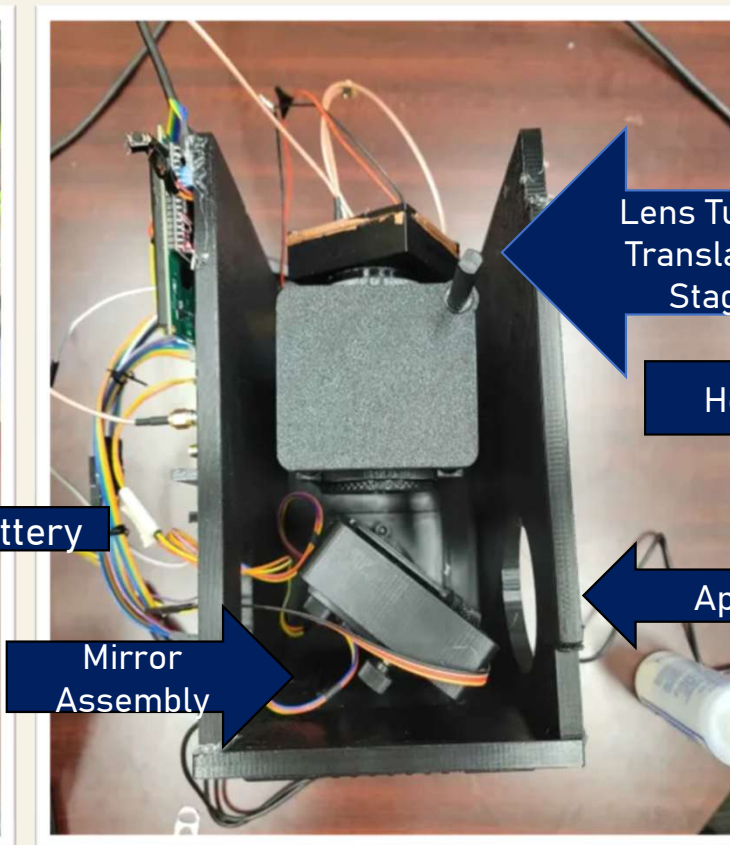
COMPLETE IRIS PROTOTYPE



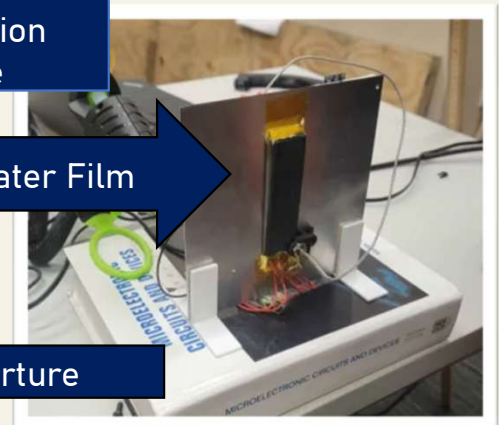
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Final Prototype



Internal Layout



Test Target/ Heat Source

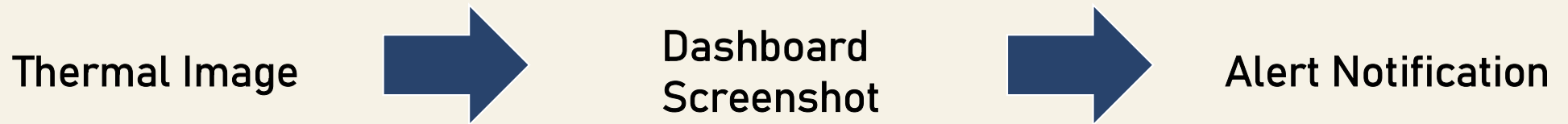
Key Features

- Integrated subsystems
- Custom PCBs and ESP32
- LCD display
- Portable battery-powered operation
- Wireless dashboard connectivity

SYSTEM OPERATION



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Operational Workflow

- Thermal image reconstructed from raster scan
- Dashboard updated with thermal data
- Hotspot alerts generated when thresholds are exceeded



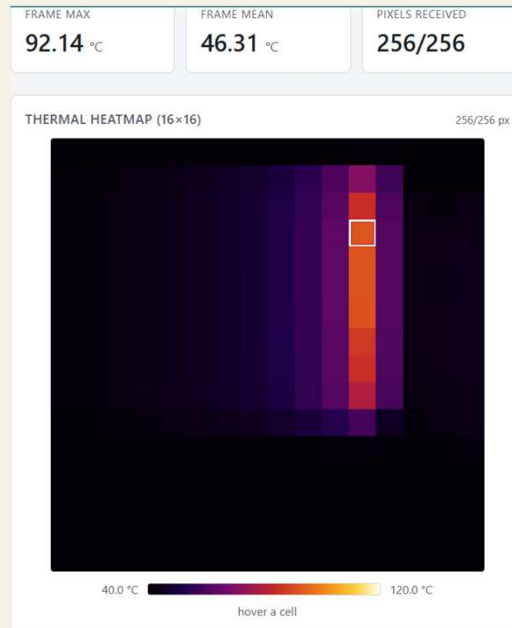
SYSTEM VALIDATION

Sub-system Validation



- Ensures mechanical and sensing are work separately
- Verify mechanical scanning before using lens assembly

Imaging Validation



- Verified integration produces sensible image
- Calibration across specified imaging range

Communication Validation



- LCD display operation
- Dashboard updates
- Wi-Fi communication



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PERFORMANCE RESULTS



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Requirement	Target	Measured	Status
Temperature Accuracy	$\pm 10^{\circ}\text{C}$	Max Error: 9.97°C	Pass
Frame Rate	≥ 0.033 fps	0.040 fps	Pass
Alert Response	≤ 30 s	0.054 s	Pass



CHALLENGES & SOLUTIONS

Challenge	Solution
Weak thermopile signal	Increasing gain, decreasing speed, sampling more
Mechanical backlash, slop	Gear design, inclusion of metal interfaces and hardware
Optical alignment	2 axis adjustable optics, calibration
EMI susceptibility	PCB layout optimization, physical shielding (faraday cage)
Temperature drift	Removing capacitance between amplifier stages
Reading lower temperature range values	Increased amplifier gain from 20,000 to 150,000



Jason Ha
PSE

BUDGET

Subsystem	Components	Cost
Optical System	CaF ₂ Lens, Gold Mirror	\$413.02
Thermal Sensing	HMS J21 Thermopile sensor	\$29.20
Motion Control	Stepper Motors, Drivers	\$11.90
Processing & Sensors	ESP32, MCP9808, Accelerometer	\$41.98
Power System	Li-Ion Batteries, Regulators	\$11.98
Mechanical Components	Filament, other hardware	\$12.99
PCB Fabrication	Main, Amplifier, Encoder, Stepper, Regulator PCBs + Stencils	\$104.85
Total		\$625.92



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WORK DISTRIBUTION

Team Member	Major	Primary Responsibilities	Secondary Responsibilities
Shea Meyer	Computer Engineering	• Microcontroller Integration • Sensor Data Processing • IoT & Web Functionality	• Servo & Mirror Coordination
Jason Ha	Photonic Science & Engineering	• Optical System Design • Optomechanical Design & Alignment	• Image Processing & Display • Optical/Imaging System Calibration • Optoelectronic Design
Sean Willie	Electrical Engineering	• PCB Design	• Power Supply Design • Enclosure Design
Andrew VanAuken	Electrical Engineering	• Protection Circuitry	• Display & UI • Auxiliary Temperature & Vibration Sensors



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